

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. *(Cancelled)*

2. *(Previously Presented)* A method for producing, on a substrate, an electronic component with closely adjacent electrodes, the method comprising:
 - depositing a first metal layer onto the substrate;
 - structuring a first photo lacquer on a surface of the first metal layer, wherein a portion of the surface of the first metal layer does not have the first photo lacquer thereon;
 - etching the portion of the surface of the first metal layer not having the first photo lacquer;
 - undercut etching the first metal layer so that an overhang is defined by the first photo lacquer;
 - exposing, to a metal vapor, a surface of the first photo lacquer and an exposed portion of the substrate where the first metal layer was etched away so that a second metal layer is formed on the surface of the first photo lacquer and the exposed portion of the substrate where the first metal layer was etched away except in a space between the overhang and the substrate;
 - removing the second metal layer from the surface of the first photo lacquer and removing the first photo lacquer;

etching a hole into the substrate at a position other than a position of the first metal layer and the second metal layer;
depositing a third metal layer onto the substrate, the first metal layer, and the second metal layer;
applying an insulator onto the third metal layer;
applying an organic semiconductor onto the third metal layer and the insulator; and
applying a sealing layer onto the organic semiconductor.

3-12. (*Cancelled*)

13. (*Previously Presented*) The method of claim 2, further comprising:
making the third metal layer from gold.

14-25. (*Cancelled*)

26. (*Previously Presented*) The method of claim 2, wherein said structuring comprises structuring the first photo lacquer on the surface of the first metal layer so that the first photo lacquer is in direct physical contact with the surface of the first metal layer.

27-40. (*Cancelled*)